5 é / Descriptions

SOD-123 .> / / x l 9 8 â ’ož

Zener Diode in a SOD-123 Plastic Package.

¤ ª / Features

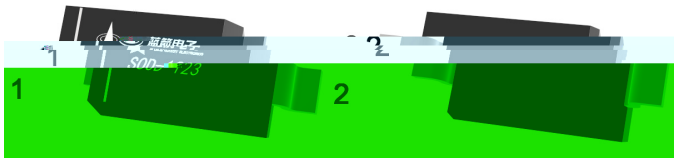
S = ô k ˆ v É Ì Á x k —)í D }ož

500mW power dissipation, medium current, automated assembly processes, HF Product.

Ð ÷ / Applications

9 < < ! 8 l 9 èož

2.4V to 39V wide zener voltage range applications.



PIN1:Cathode PIN2:Anode

, M V / Marking

• - ~ ª ¢ož

See Marking Instructions.

@ *f* Parameter	… Z Symbol	*f* › Rating	% y Unit
Forward Voltage (Note 2) I_F=10mA	V_F	0.9	V
Power Dissipation(Note 1)	P_D	500	mW
Typical Thermal Resistance Junction to Ambient(Note 1)	R $_{JA}$	305	/W
Junction and Storage Temperature Range	T_j,T_{stg}	-65 150	

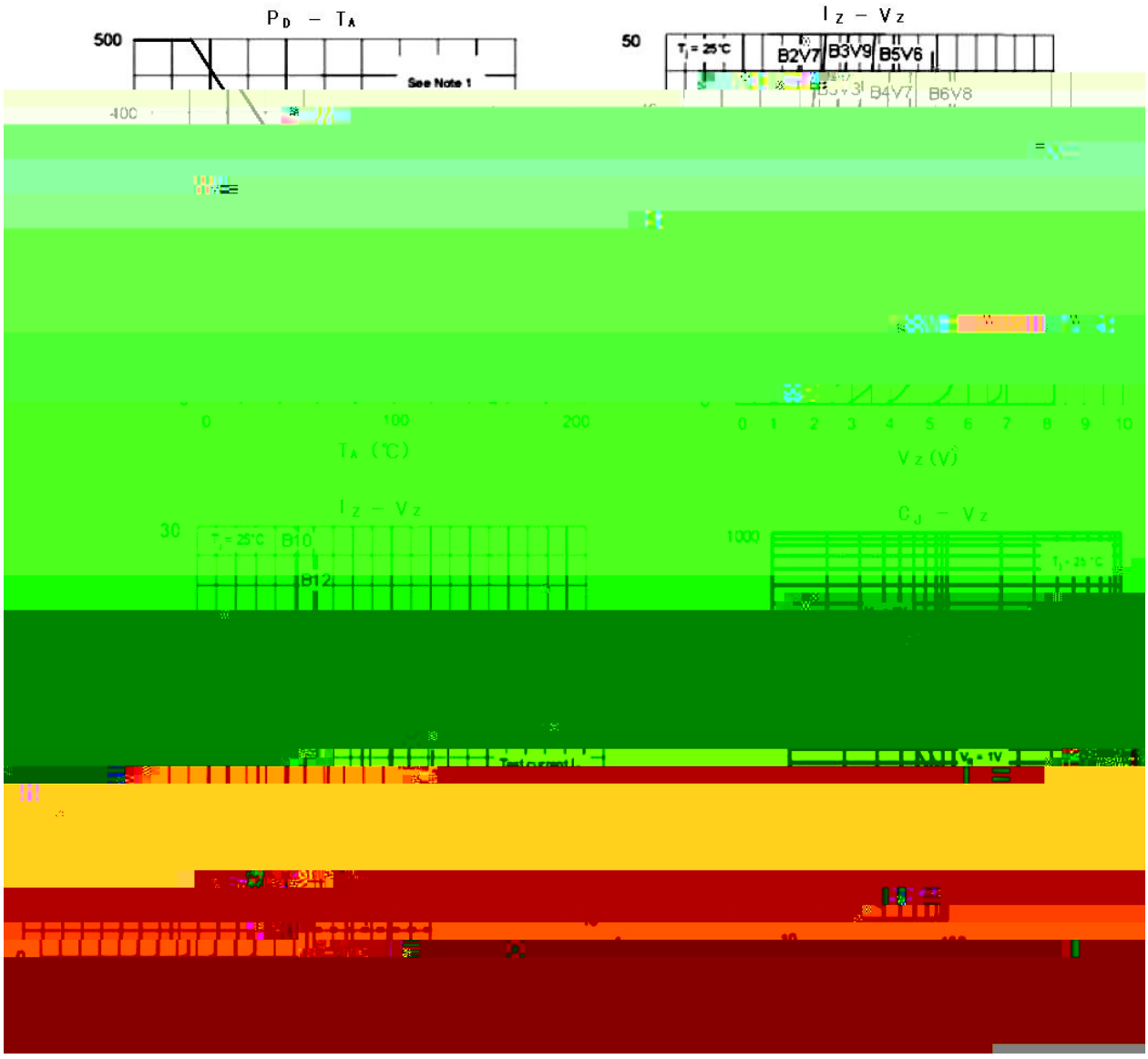
Type Number	Mark-ing Code	Zener Voltage Range				Maximum Zener Impedance			Maximum Reverse Current	
		V_z @I_{ZT}			I_{ZT}	Z_{ZT} @I_{ZT}	Z_{ZK} @I_{ZK}	I_{ZK}	I_R	@V_R
		Nom (V)	Min (V)	Max (V)	mA			mA	A	V

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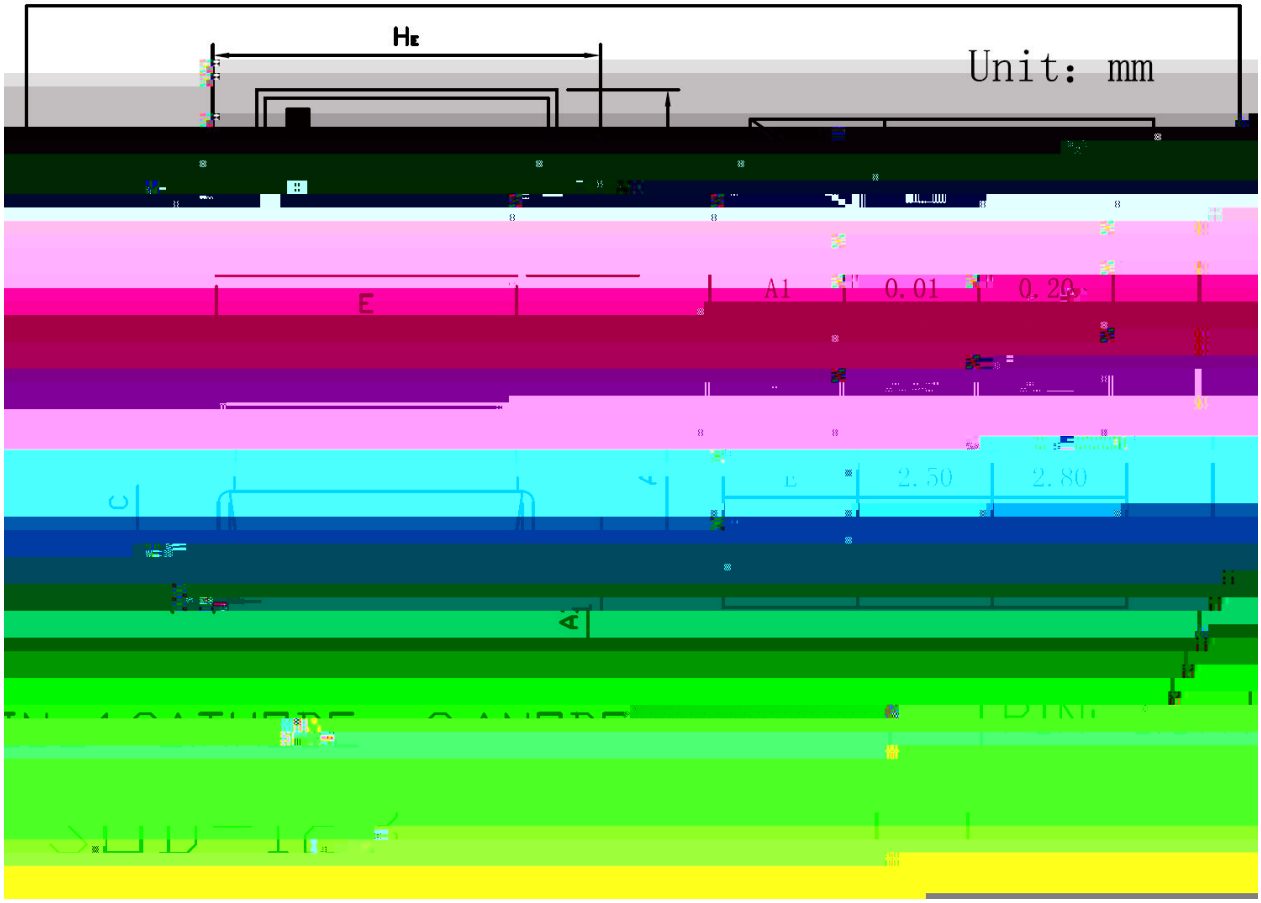
Notes:

1. Device mounted on ceramic PCB; 7.6mm x 9.4mm x 0.87mm with pad areas 25mm^2.
2. Short duration test pulse used to minimize self-heating effect.
3. f = 1kHz.

Ô ? d • Ž ¢ / Electrical Characteristic Curve



Ø ¤ =) ¢ / Package Dimensions



BZT52BXXX

š WD t … • Ž ¢ (x /) / : K S V K X G Z [X K 6 X U L O R K L U X / 8 8 K L R U] 9 U R J K X O T M 6

ª ¢ y

1o• Ä ½ “ † 150 ½180 - k ž • 60 ½90sec;

2o• Q › “ † 245 r 5 - k ž • 4 Ò 5 r 0.5sec;

3o•D N ò i Ò 0 , † 2 ½10 - /sec.

Note:

1.Preheating:150~180 - , Time:60~90sec.

2.Peak Temp.:245 r 5 - , Duration:5 r 0.5sec.

3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

“ † y 260 r 5 - ž • y 10 r 1 sec. Temp.:260±5 Time:10±1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type 7>û ˜ E	Units ;>û ¦H	Dimension ;>û p . (unit ÆEmm³)